

光鋳科技股份有限公司
Epileds Technologies, Inc.
 Product specification of 9 x 7 mil blue LED chip

1. Scope:

This specification applies to InGaN/GaN 9 x 7 mil blue LED chip, EL-B0907A-A1 ◦

2. Materials :

2.1 P-contact : Conductive Layer ◦

2.2 P-pad : Au ◦

2.3 N-pad : Au ◦

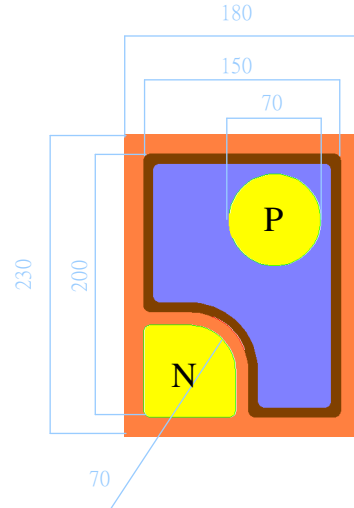
3. Dimensions :

3.1 Chip size : $230 \pm 20 \mu\text{m} \times 180 \pm 20 \mu\text{m}$ ◦

3.2 P-pad : $\phi 70 \pm 10 \mu\text{m}$, thickness $1.2 \pm 0.1 \mu\text{m}$ ◦

3.3 N-pad : $\phi 70 \pm 10 \mu\text{m}$, thickness $1.2 \pm 0.1 \mu\text{m}$ ◦

3.4 Chip thickness : $90 \mu\text{m} \pm 10 \mu\text{m}$ ◦



4. Electro-optical characteristics and specification: (Tc=25°C)

4.1 Electro-optical characteristics

Test parameter	Condition	Min	Typ	Max	Unit
Dominant wavelength(Wd)	5mA	447.5	-	480	nm
Luminous intensity(Iv)	5mA	1	-	150	mcd
Forward voltage(Vf4)	1uA	1.9	-	2.5	V
Forward voltage(Vf1)	5mA	2.5	-	3.5	V
Reverse current (Ir)	-8V	0	-	0.5	uA
Electrostatic discharge characteristic (ESD)	HBM	1000	-	-	V

4.2 Electro-optical specification(Bin table) :

Wd		Iv		Vf1 (V)	Vf4 (V)	Ir (uA)
Bin	nm	Bin	mcd			
PT	447.5~450	01	1~12	2.5~3.5	1.9~2.5	0~0.5
BA	450~452.5	02	12~16			
BB	452.5~455	03	16~20			
BC	455~457.5	04	20~25			
BD	457.5~460	05	25~32			
BE	460~462.5	06	32~40			
BF	462.5~465	07	40~50			
BG	465~467.5	08	50~60			
BH	467.5~470	09	60~75			
BI	470~472.5	10	75~90			
BJ	472.5~475	11	90~105			
BK	475~477.5	12	105~125			
BL	477.5~480	13	125~150			

Rev.: 10/22/2008

* The detail technical and reliability datasheet are also available for your reference, please be free to contact us.

Form No:PP-006-06(01)